



SPN80N10A

N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN80N10A is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application , notebook computer power management and other battery powered circuits where high-side switching .

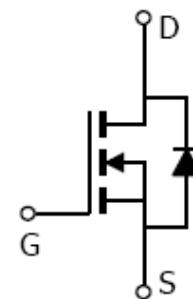
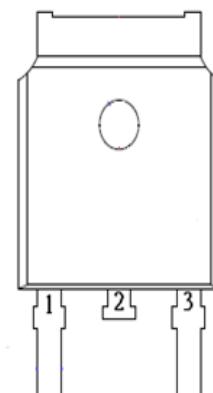
APPLICATIONS

- DC/DC Converter
- Load Switch
- Synchronous Buck Converter
- SMPS Secondary Side Synchronous Rectifier
- Power Tool
- Motor Control

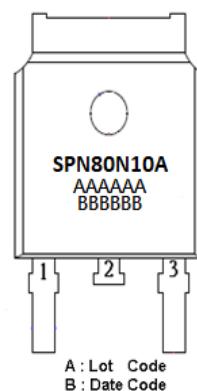
FEATURES

- ◆ 100V/74A,R_{DS(ON)}=8.0mΩ@V_{GS}=10V
- ◆ 100V/74A,R_{DS(ON)}=10.5mΩ@V_{GS}=4.5V
- ◆ Super high density cell design for extremely low R_{DS(ON)}
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ TO-252-2L package design

PIN CONFIGURATION(TO-252-2L)



PART MARKING





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PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN80N10AT252RGB	TO-252-2L	SPN80N10A

※ SPN80N10AT252RGB : 13" Tape Reel ; Pb – Free ; Halogen – Free

ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	100	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current(Silicon Limited)	T _C =25°C	74	A
	T _C =100°C	47	
Pulsed Drain Current	I _{DM}	260	A
Avalanche Energy, Single Pulse (L=0.4mH , T _C =25°C)	E _A S	245	mJ
Power Dissipation	P _D	93	W
Operating Junction Temperature	T _J	-55/150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Case	R _{θJC}	1.35	°C/W

Note :

The maximum current rating is package limited at 70A for TO-252-2L



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ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, ID=250uA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , ID=250uA	1.4	1.7	2.4	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V T _J =25°C			1	uA
		V _{DS} =80V, V _{GS} =0V T _J =100°C			100	
Drain-Source On-Resistance	R _{D(on)}	V _{GS} =10V, ID=20A		6.5	8	mΩ
		V _{GS} =4.5V, ID=10A		8.8	10.5	
Forward Transconductance	g _f	V _{DS} =5V, ID=10A		60		S
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =Open, f=1MHz		1.3		Ω
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V		0.9	1.2	V
Dynamic						
Total Gate Charge	Q _{g(10V)}	V _{DS} =50V, V _{GS} =10V ID=20A		32		nC
Total Gate Charge	Q _{g(4.5V)}			16		
Gate-Source Charge	Q _{gs}			6		
Gate-Drain Charge	Q _{gd}			4		
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V f=1MHz		1876		pF
Output Capacitance	C _{oss}			348		
Reverse Transfer Capacitance	C _{rss}			5.6		
Turn-On Time	t _{d(on)}	V _{DD} =50V, ID=20A, V _{GS} =10V R _G =10Ω		7		nS
	t _r			4		
Turn-Off Time	t _{d(off)}			20		
	t _f			3		



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TYPICAL CHARACTERISTICS

Fig 1. Typical Output Characteristics

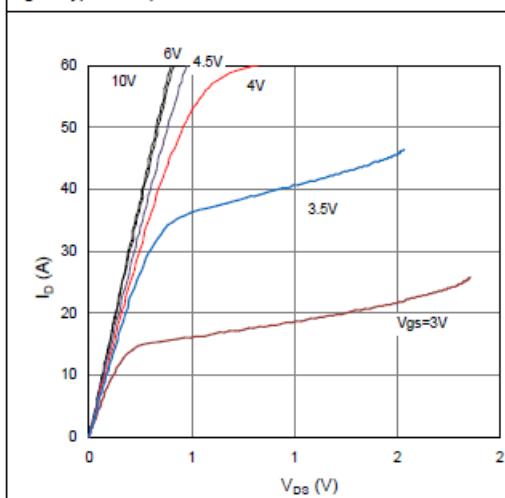


Figure 2. On-Resistance vs. Gate-Source Voltage

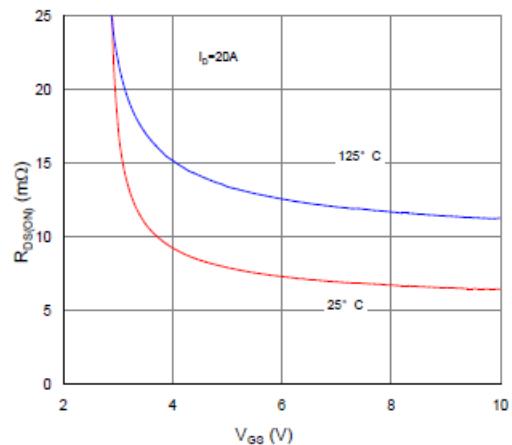


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

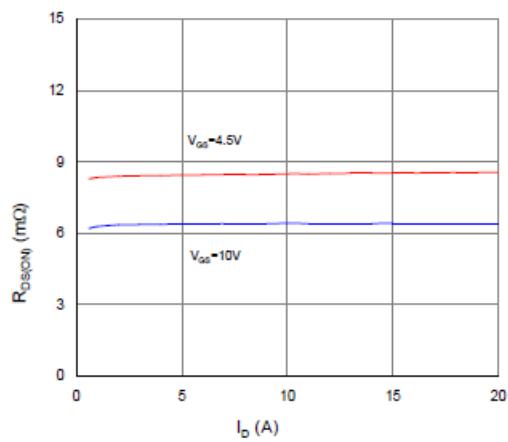


Figure 4. Normalized On-Resistance vs. Junction Temperature

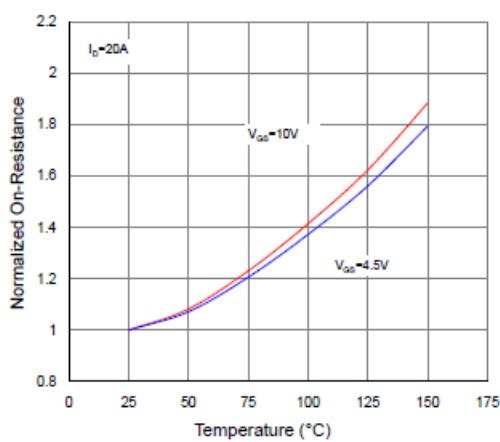


Figure 5. Typical Transfer Characteristics

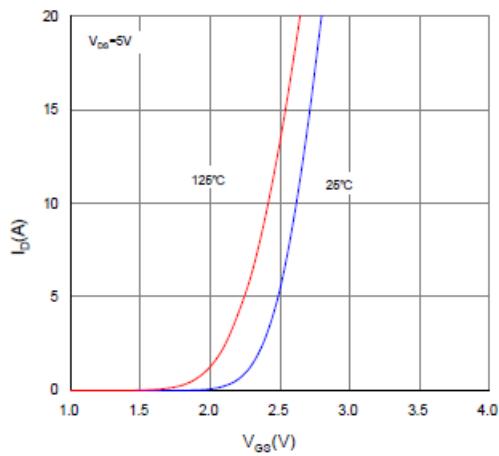
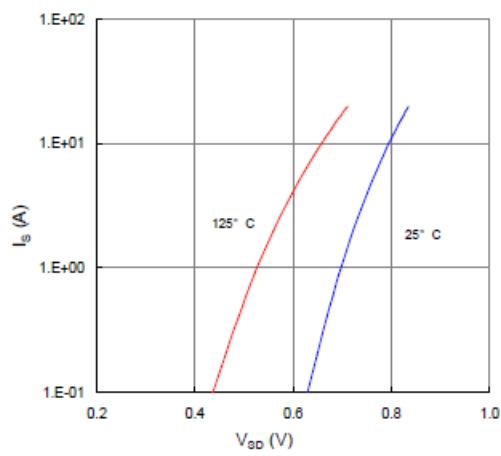


Figure 6. Typical Source-Drain Diode Forward Voltage





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TYPICAL CHARACTERISTICS

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

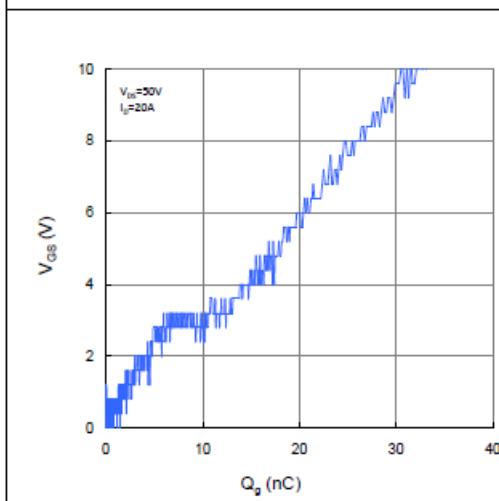


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

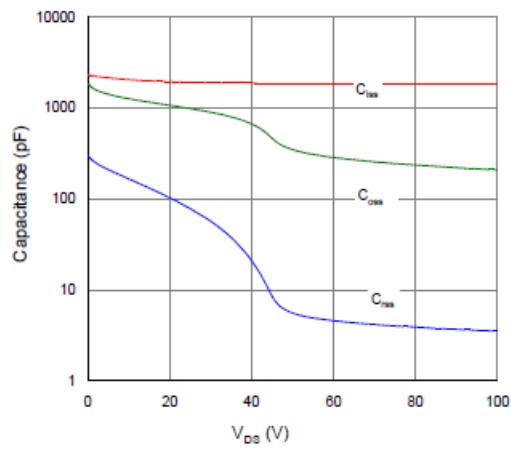


Figure 9. Maximum Safe Operating Area

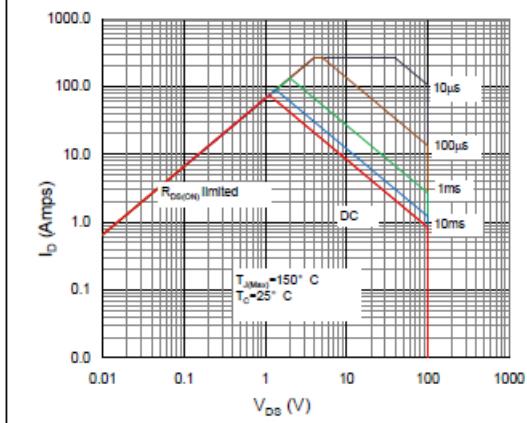


Figure 10. Maximum Drain Current vs. Case Temperature

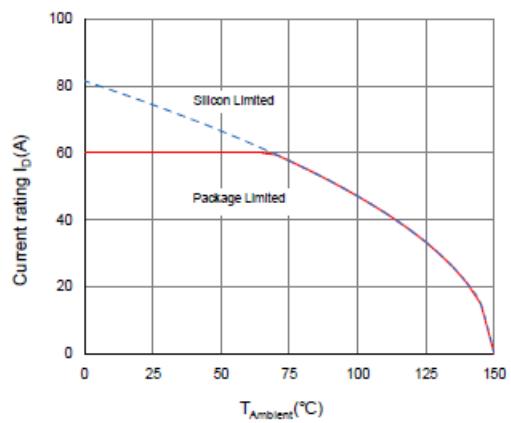
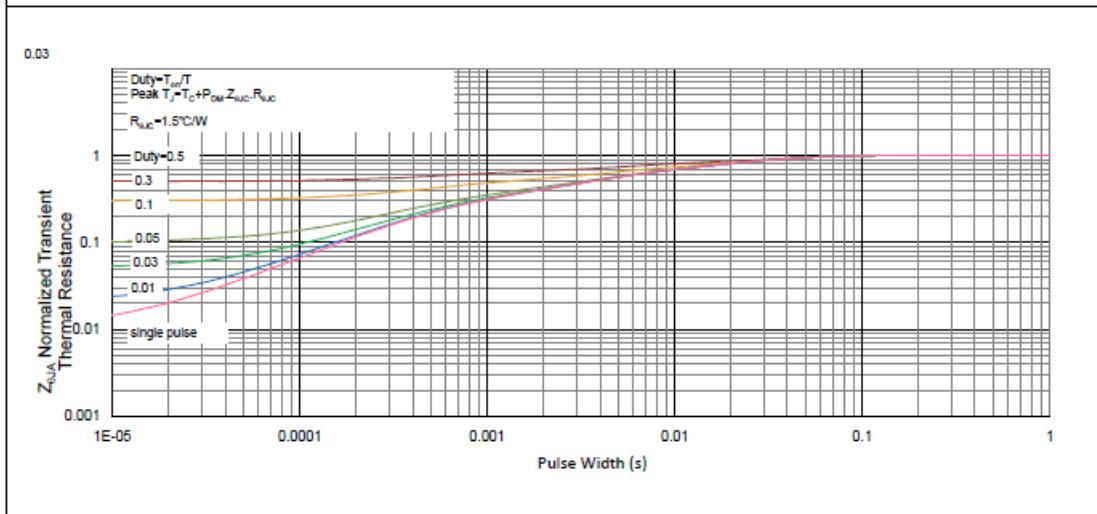


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient





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